

SOT1310-1

plastic, extremely thin quad flat package; no leads; 0.4 mm pitch; 3.4 mm x 2.5 mm x 0.5 mm body

12 May 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN24
Package type industry code	XQFN24
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-288
Mounting method type	S (surface mount)
Issue date	22-8-2011
Manufacturer package code	SOT1310

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	3.3	-	3.4	3.5	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	24	-	



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2. Package outline

XQFN24: plastic, extremely thin quad flat package; no leads; 24 terminals; body 2.5 x 3.4 x 0.5 mm

SOT1310-1

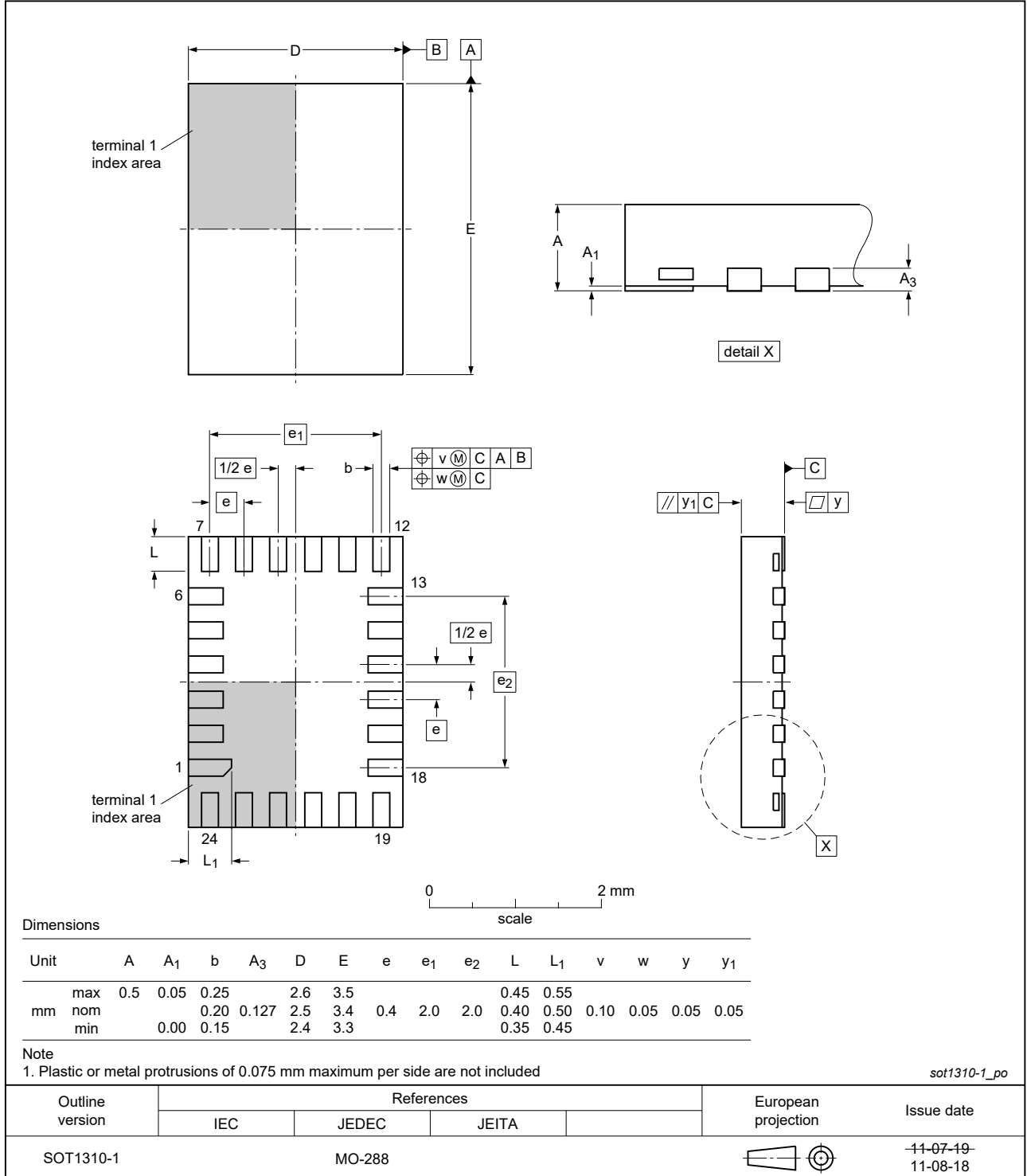
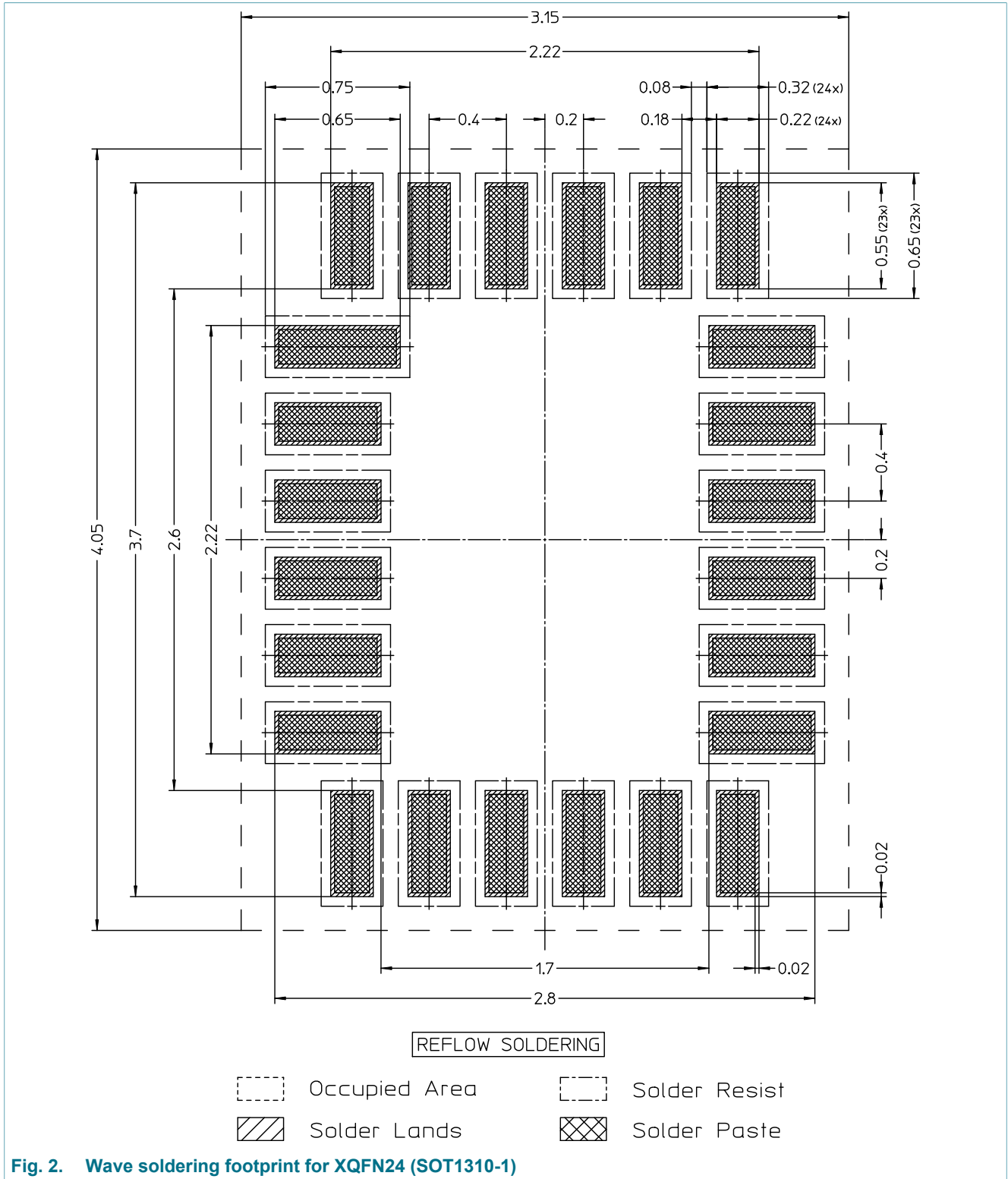


Fig. 1. Package outline XQFN24 (SOT1310-1)

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3. Soldering



plastic, extremely thin quad flat package; no leads; 0.4 mm pitch; 3.4 mm x 2.5 mm x 0.5 mm body

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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